



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: 98 P7501 US 01

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In re the application of: )  
Ramachandran et al. ) Group Art: 1746  
Serial No.: 09/204,706 ) Examiner: A. Olsen  
Filing Date: December 3, 1998 )  
Title: REMOVAL OF POST-RIE POLYMER) ON Al/Cu METAL LINE )

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AMENDMENT UNDER 37 C.F.R. §1.115

Honorable Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed December 18, 2001, which rejected the claims in the above-identified patent application, applicants respectfully request reconsideration, based upon the amendments hereinafter set forth.

IN THE CLAIMS:

13. (Thrice Amended) In a metal etch tool for removing post-RIE polymer rails formed on a Al/Cu metal line of a semiconductor structure, the improvement comprising an integrated metal etch tool comprising therein:

a) strip chamber means for water only plasma to strip [the] photo-resist [layer] of a semiconductor composite structure [with water only plasma] subsequent to a RIE to limit thickness of sidewall polymer;

b) vacuum chamber means to chemically modify